

METHOD FOR DICING WAFER

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ABSTRACT OF THE DISCLOSURE

10 A method for dicing a wafer, in which a wafer having
a plurality of electronic circuits formed at one side
thereof is diced into individual semiconductor chips, the
method comprising the steps of:

coating the side of the wafer opposed to the
side at which the plurality of electronic circuits are
formed with a layer of a photosensitive resist,

15 exposing the photosensitive resist layer by
irradiating it with a radiation capable of penetrating
the wafer, at the side having the electronic circuits
formed, and along the dicing lines, for subsequently
cutting the wafer for the dicing,

20 developing the photosensitive resist layer to
thereby selectively remove the material at the exposed
portions of the resist layer along the dicing lines, and

dicing the wafer by etching it, at the side
opposed to the side having the electronic circuits, to
25 cut the wafer along the dicing lines.